



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**Applicant(s):** Douglas D. Coolbaugh, et al.

**Examiner:** Unassigned

**Serial No:** 10/707,064

**Art Unit:** Unassigned

**Filed:** 11/19/2003

**Docket:** BUR920020119US1 (16763)

**For:** OPTIMUM PADSET FOR WIRE  
BONDING RF TECHNOLOGIES WITH  
HIGH-Q INDUCTORS

**Dated:** November 11, 2003

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

Sir:

In accordance with 37 C.F.R. §§ 1.97 and 1.98, it is requested that the six (6) references, which are listed on the attached Form PTO-1449, be made of record in the above-identified case.

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**CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents, P. O. Box 1450, Alexandria, VA 22313-1450 on

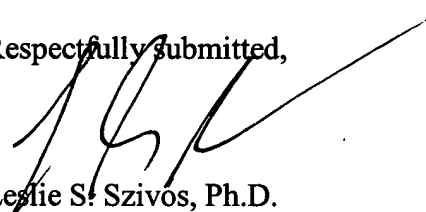
**Dated:** 1/21/04

*Maryann Luisi*  
Maryann Luisi

Applicants are submitting copies of the above-cited references.

Inasmuch as this Information Disclosure Statement is being submitted in accordance with the schedule set out in 37 C.F.R. § 1.97(b), no statement or fee is required.

Respectfully submitted,



Leslie S. Szivos, Ph.D.  
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LSS/sf  
Enclosures    PTO 1449  
Six (6) references

**LIST OF PRIOR ART  
CITED BY APPLICANT**

(Use several sheets if necessary)

**Atty. Docket N .**  
BUR920020119US1 (16763)**Serial No.****Applicant**  
Douglas D. Coolbaugh, et al**Filing Date****Group**  
Unassigned**U.S. PATENT DOCUMENTS**

EXAMINER INITIAL*		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (if appropriate)
	AA						
	AB						

**FOREIGN PATENT DOCUMENTS**

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
		JP5-047859A	2/26/1993	JAPAN				

**OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)**

	S.G. Bombardier, et al. (1997) "Aluminum-Tungsten-Aluminum Sandwich for Semiconductor Chip Wirebond Pad", IBM Technical Disclosure Bulletin, Vol. 40, No. 6, page 131;
	C.R. Fedorko, Jr., et al. (1984) "Packaging Substrate with Top Surface Metallurgy Adapted for Mixed Technology Device Bonding and Method", IBM Technical Disclosure Bulletin, Vol. 26, No. 12, page 6624;
	D. Chance, et al. (1993) "Thin Film Metallurgical Structure and Wire for Engineering Chance", IBM Technical Disclosure Bulletin, Vol. 36, No. 1, page 41;
	T.H. Chiles (1989) Abstract of Disclosure No. 30581 entitled "Use of a Composite Metal Pad for Wirebond connection to the Copper Core of a Metal Core Substrate Circuit Board" Kenneth Mason Publications, Ltd. England, No. 305 (1 page); and
	R. J. Bergeron, et al. (1992) Abstract of Disclosure No. 34237 entitled "Bond Pad Metallurgy for Wire Bonding", Kenneth Mason Publications, Ltd. England, No. 342 (1 page).

**EXAMINER****DATE CONSIDERED**

\* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.